FLL57MK

L-Band Medium & High Power GaAs FET

FEATURES

- High Output Power: P_{1dB} = 36.0dBm (Typ.)
- High Gain: G_{1dB} = 11.5dB (Typ.)
- High PAE: $\eta_{add} = 37\%$ (Typ.)
- Proven Reliability
- Hermetically Sealed Package

DESCRIPTION

The FLL57MK is a Power GaAs FET that is specifically designed to provide high power at L-Band frequencies with gain, linearity and efficiency superior to that of silicon devices. The performance in multitone environments for Class AB operation make them ideally suited for base station applications.

Fujitsu's stringent Quality Assurance Program assures the highest reliability and consistent performance.



ABSOLUTE MAXIMUM RATING (Ambient Temperature Ta=25°C)

| Item | Symbol | Condition | Rating | Unit |
|-------------------------|------------------|-----------------------|-------------|------|
| Drain-Source Voltage | V _{DS} | | 15 | V |
| Gate-Source Voltage | VGS | | -5 | V |
| Total Power Dissipation | PT | $T_{C} = 25^{\circ}C$ | 21.4 | W |
| Storage Temperature | T _{stg} | | -65 to +175 | °C |
| Channel Temperature | T _{ch} | | 175 | °C |

Fujitsu recommends the following conditions for the reliable operation of GaAs FETs:

1. The drain-source operating voltage (V_{DS}) should not exceed 10 volts.

2. The forward and reverse gate currents should not exceed 32.2 and -2.2 mA respectively with

gate resistance of 100Ω .

3. The operating channel temperature (T_{ch}) should not exceed 145°C.

ELECTRICAL CHARACTERISTICS (Ambient Temperature Ta=25°C)

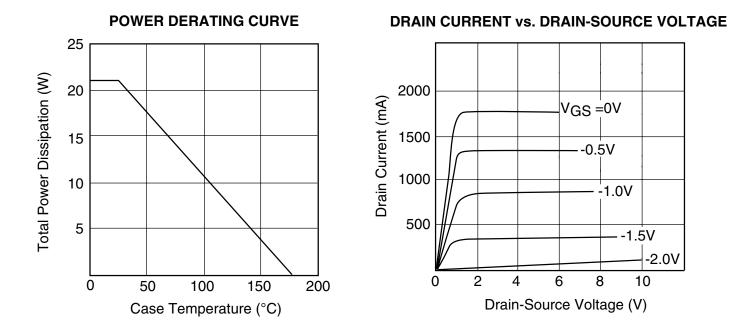
| ltom | Cumhal | Test Conditions | Limit | | | llmit | |
|-------------------------------|------------------|---|-------|------|------|-------|--|
| Item | Symbol | | Min. | Тур. | Max. | Unit | |
| Saturated Drain Current | IDSS | $V_{DS} = 5V, V_{GS} = 0V$ | - | 1800 | 2700 | mA | |
| Transconductance | 9m | $V_{DS} = 5V, I_{DS} = 1100mA$ | - | 1000 | - | mS | |
| Pinch-off Voltage | Vp | $V_{DS} = 5V, I_{DS} = 90mA$ | -1.0 | -2.0 | -3.5 | V | |
| Gate Source Breakdown Voltage | VGSO | IGS = -90μΑ | -5 | - | - | V | |
| Output Power at 1dB G.C.P. | P1dB | | 35.5 | 36.0 | - | dBm | |
| Power Gain at 1dB G.C.P. | G _{1dB} | VDS = 10V IDS = 0.55IDSS (Typ.), f = 2.3GHz | 10.5 | 11.5 | - | dB | |
| Power-added Efficiency | nadd | | - | 37 | - | % | |
| Thermal Resistance | R _{th} | Channel to Case | - | 6.2 | 7.0 | °C/W | |

CASE STYLE: MK

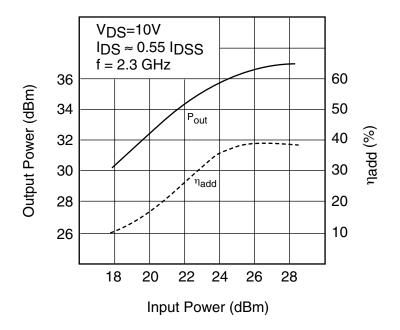
Edition 1.1 July 1999 G.C.P.: Gain Compression Point





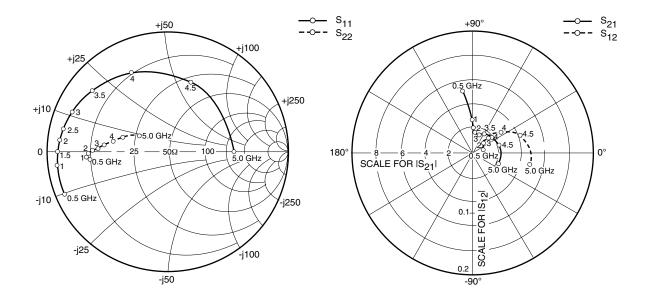


OUTPUT POWER vs. INPUT POWER





FLL57MK — L-Band Medium & High Power GaAs FET

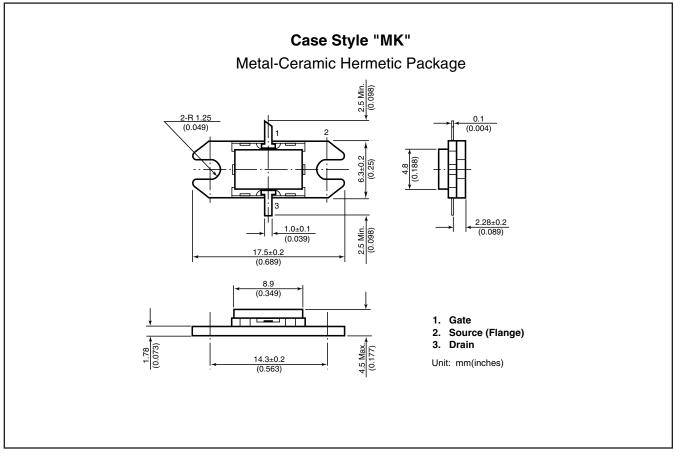


S-PARAMETERS

| V _{DS} = 10V, I _{DS} = 800mA | | | | | | | | | |
|--|------|--------|-------|-------|------|-------|------|--------|--|
| FREQUENCY | S11 | | S2 | S21 | | S12 | | S22 | |
| (MHZ) | MAG | ANG | MAG | ANG | MAG | ANG | MAG | ANG | |
| | | | | | | | | | |
| 500 | .929 | -157.5 | 5.115 | 99.7 | .017 | 21.7 | .661 | -175.9 | |
| 1000 | .927 | -172.6 | 2.718 | 91.4 | .018 | 24.6 | .669 | -176.5 | |
| 1500 | .914 | 179.9 | 1.988 | 88.3 | .020 | 34.4 | .660 | -177.7 | |
| 2000 | .902 | 174.0 | 1.653 | 83.8 | .022 | 41.1 | .651 | -178.8 | |
| 2500 | .887 | 167.6 | 1.558 | 79.4 | .026 | 48.7 | .621 | 179.8 | |
| 3000 | .856 | 157.0 | 1.534 | 72.3 | .034 | 42.7 | .584 | 177.7 | |
| 3500 | .806 | 140.9 | 1.782 | 60.2 | .040 | 47.0 | .527 | 174.3 | |
| 4000 | .725 | 114.8 | 1.888 | 39.3 | .057 | 35.5 | .465 | 169.3 | |
| 4500 | .609 | 71.9 | 2.199 | 15.8 | .082 | 19.7 | .396 | 162.0 | |
| 5000 | .548 | -0.6 | 2.278 | -24.0 | .096 | -11.8 | .270 | 151.1 | |



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CAUTION

Fujitsu Compound Semiconductor Products contain **gallium arsenide** (GaAs) which can be hazardous to the human body and the environment. For safety, observe the following procedures:

- Do not put these products into the mouth.
- Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by-products are dangerous to the human body if inhaled, ingested, or swallowed.
- Observe government laws and company regulations when discarding this product. This product must be discarded in accordance with methods specified by applicable hazardous waste procedures.

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